

Welcome to E-XFL.COM

Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	20 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	-
Number of Macrocells	10
Number of Gates	-
Number of I/O	-
Operating Temperature	0°C ~ 75°C (TA)
Mounting Type	Through Hole
Package / Case	24-DIP (0.300", 7.62mm)
Supplier Device Package	24-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/gal20ra10b-20lp

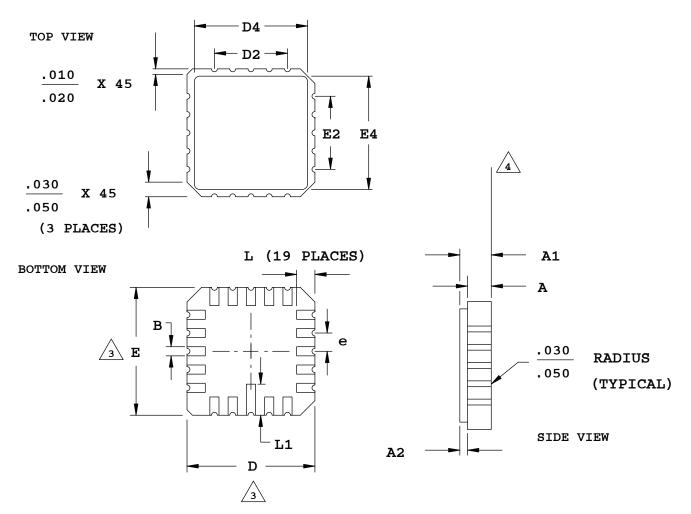
Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



20-Pin LCC Package

Dimensions in Inches



NOTES:

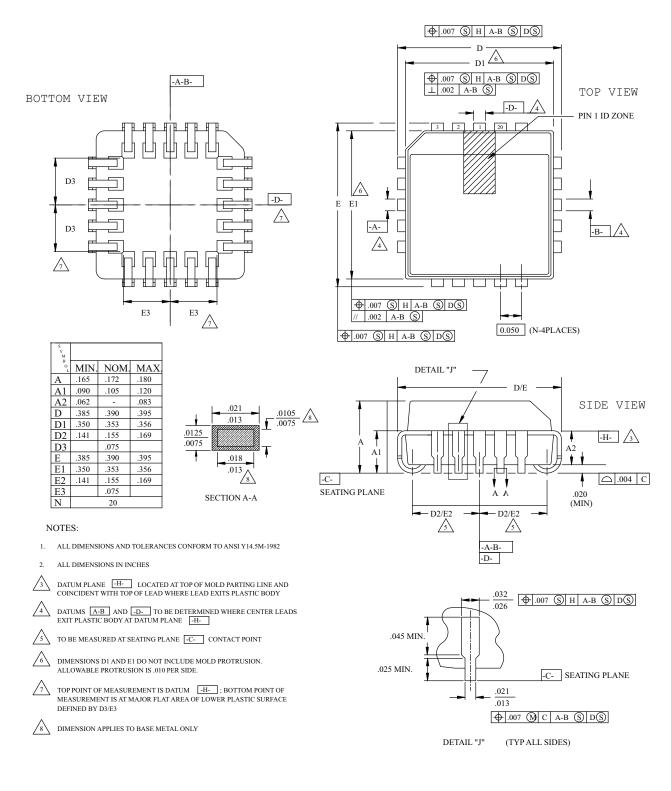
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5.
- 2. ALL DIMENSIONS ARE IN INCHES.
- 3. DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .010 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .005 INCHES MAXIMUM PER SIDE.
- 4. FLATNESS TOLERANCE IS .004 INCHES PER INCH.

INCHES		
MIN.		MAX.
.054		.074
.064		.089
.007		.015
.022		.028
.342		.358
.200		
.270		.315
.342		.358
	.200	
.270		.315
.050 BSC		
.042		.058
.075		.095
	MIN. .054 .064 .007 .022 .342 .270 .342 .270 .00 .042	MIN. .054 .064 .007 .022 .342 .200 .270 .342 .200 .270 .200 .270 .200 .270 .200 .270 ■



20-Pin PLCC Package

Dimensions in Inches





28-Pin Plastic DIP Package

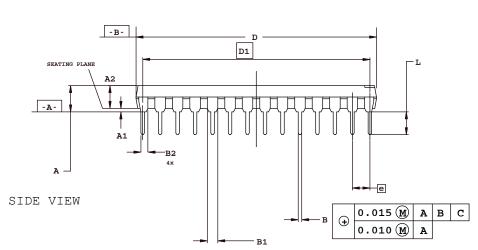
Dimensions in Inches

TOP VIEW

NOTE :

- 1 CONTROLLING DIMENSION: INCHES
- 2 DIMENSIONING AND TOLERANCING
- PER ANSI Y14.5M-1982
- 3 ALL END LEADS IN THIS FAMILY ARE 1/2 LEADS
- 4 DIMENSION A, A1, AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3
- 5 D AND E1 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH AND PROTRUSION SHALL NOT EXCEED 0.010
- 6 E AND EA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO PLANE A
- 7 eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED. eC MUST BE ZERO OR GREATER
- 8 N IS THE NUMBER OF TERMINAL POSITIONS
- 9 B1 AND B2 MAXIMUM DIMENSIONS DO NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED 0.010

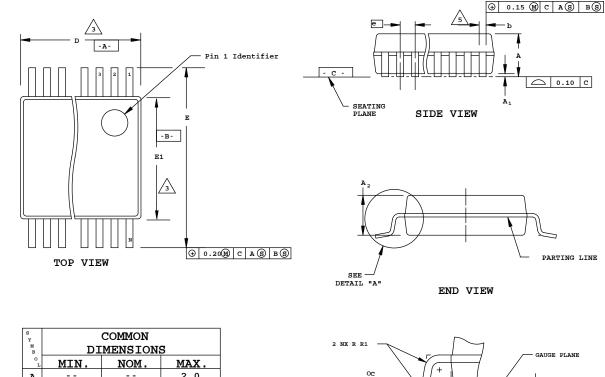
S Y M B	INCHES		
0 L			
Α	-	-	.180
A ₁	.015	-	-
\mathbf{A}_{2}	.120	.135	.150
в	.014	.018	.022
B¹	.045	.050	.060
B ₂	.030	.040	.045
С	.008	.010	.015
D	1.345	1.365	1.385
D1	1	.300 BS	SC
Е	.300	.310	.325
E 1	.275	.285	.295
е		100 BSC	2
e,		300 BSC	2
ев	-	-	.430
e _c	.000	-	.060
Г	.110	.130	.150
N		28	





28-Pin SSOP Package

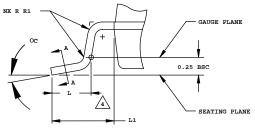
Dimensions in Millimeters



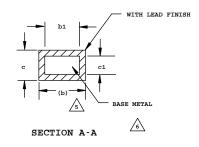
M B	DIMENSIONS			
0 L	MIN.	NOM.	MAX.	
A			2.0	
A ₁	0.05			
\mathbf{A}_{2}	1.65	1.75	1.85	
b	0.22	-	0.38	
b1	0.22	0.30	0.33	
С	0.09		0.25	
C 1	0.09	0.15	0.21	
D	9.90	10.20	10.50	
E1	5.00	5.30	5.60	
е		0.65 BSC		
Е	7.40	7.80	8.20	
L	0.55	0.75	0.95	
L1		1.25 REF.		
N		28		
oc	0	4	8	
R1	0.09			

NOTES:

- 1. CONTROLLING DIMENSION: MILLIMETERS.
- 2. DIMENSIONING & TOLERANCES PER ANSI.Y14.5M-1982.
- A. "D" & "E1" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DO INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.20mm PER SIDE.
- 4. TO BE DETERMINED AT THE SEATING PLANE



DETAIL 'A'

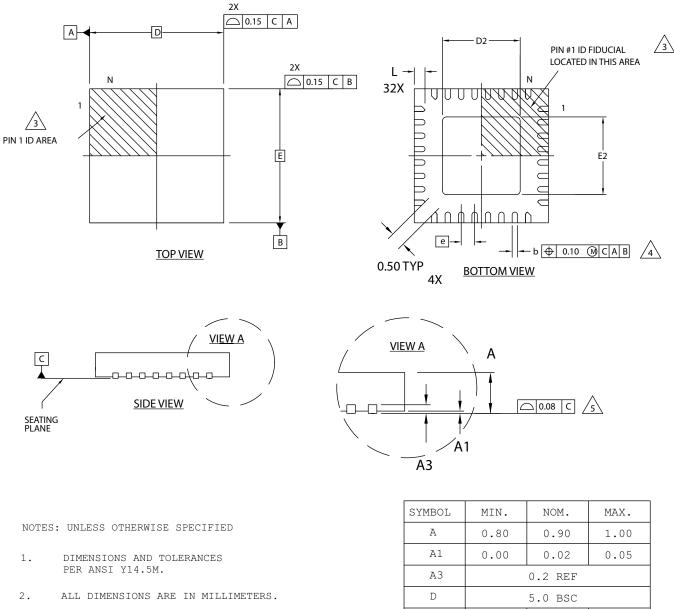


- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13mm TOTAL IN EXCESS OF b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR INTRUSION SHALL NOT REDUCE DIMENSION b BY MORE THAN 0.07mm AT LEAST MATERIAL CONDITION.
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 & 0.25mm FROM THE LEAD TIP
- 7. "N" IS THE NUMBER OF TERMINAL POSITIONS



32-Pin QFN Package Option 1: Power Manager II, iCE40[™]

Dimensions in Millimeters



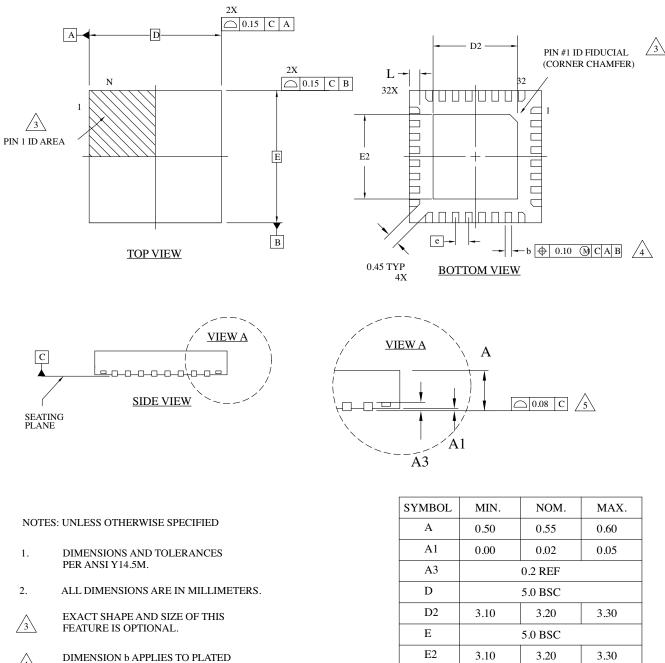
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
- /5 APPLIES TO EXPOSED PORTION OF TERMINALS.

А	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	5.0 BSC		
D2	1.25	2.70	3.75
E	5.0 BSC		
E2	1.25	2.70	3.75
b	0.18	0.24	0.30
е	0.50 BSC		
L	0.30	0.40	0.50



32-Pin QFN Package Option 2: MachXO2[™]

Dimensions in Millimeters



- 4 TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
- $\sqrt{5}$ APPLIES TO EXPOSED PORTION OF TERMINALS.

b

e

L

0.20

0.35

0.25

0.40

0.50 BSC

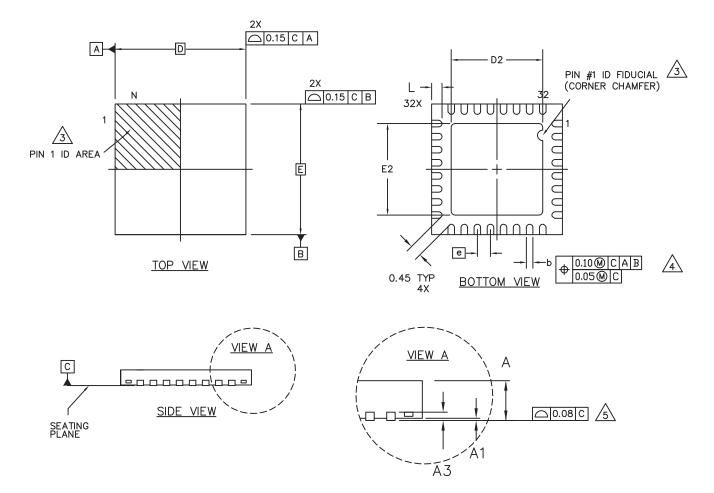
0.30

0.45



32-Pin QFN Package Option 3: MachXO2 SG32C

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

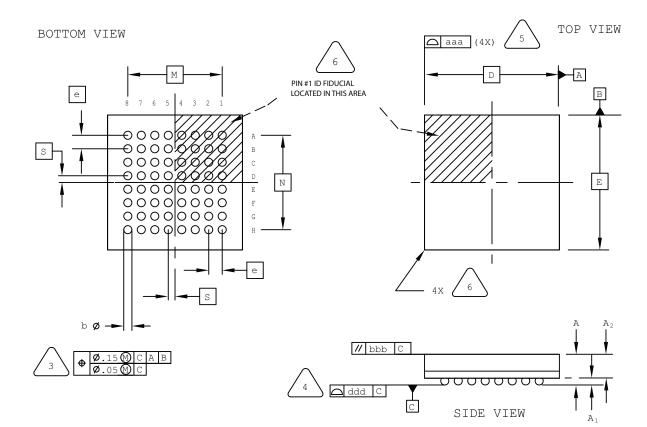
- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
- 5 APPLIES TO EXPOSED PORTION OF TERMINALS.
- 6. JEDEC REFERENCE MO-248 AND DR-4.2

SYMBOL	MIN.	NOM.	MAX.
A	0.50	0.55	0.65
A1	0.00	0.02	0.05
A3	0.2 REF		
D	5.0 BSC		
D2	3.40	3.50	3.60
E	5.0 BSC		
E2	3.40	3.50	3.60
b	0.18	0.25	0.30
е	0.50 BSC		
L	0.35	0.40	0.45



64-Ball ucBGA Package

Dimensions in Millimeters



NOTES •	UNLESS	OTHERWISE	SPECIFIED
TIOTEO.	0111100	OTHERMEDE	OT DOTT TDD

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



4

6

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

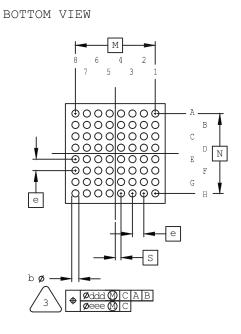
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

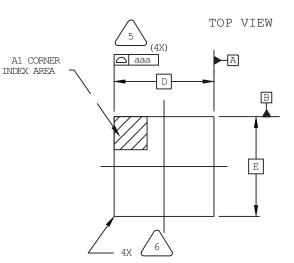
SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.10	-	_
A2	-	-	0.90
D/E	4.00 BSC		
M/N	2.80 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
е	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

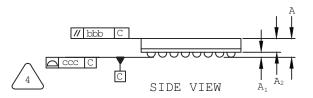


64-Ball ucfBGA Package

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

1.	DIMENSIONS AND TOLERANCES
	PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



4

5

6

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

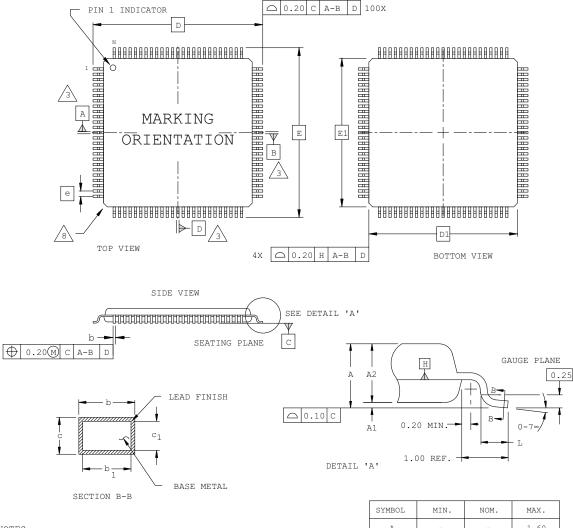
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

SYMBOL	MIN.	NOM.	MAX.
A	_	-	1.00
Al	0.11	-	-
A2	0.62	-	-
D/E		3.50 BSC	
M/N		2.80 BSC	
S	0.20 BSC		
b	0.20 0.25 0.30		
е	0.40 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee		0.08	



100-Pin TQFP Package Option 1: MachXO2, MachXO[™], ispMACH[®] 4000

Dimensions in Millimeters



NOTES:

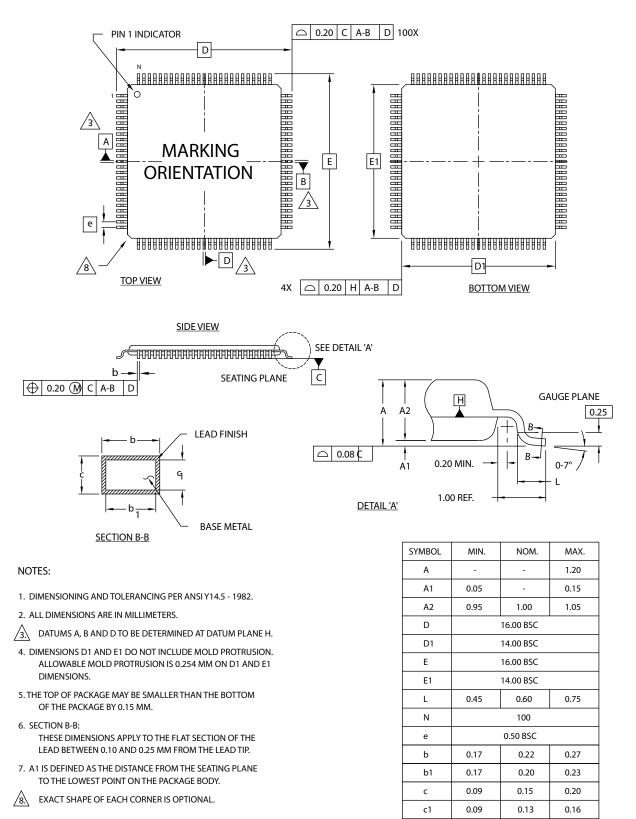
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- $/_3$ datums a, b and d to be determined at datum plane H.
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. Al is defined as the distance from the seating plane to the lowest point on the package body.
- /8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D		16.00 BSC	
D1		14.00 BSC	
E	16.00 BSC		
E1	14.00 BSC		
L	0.45 0.60 0.75		
N	100		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
с	0.09	0.15	0.20
c1	0.09	0.13	0.16



100-Pin VQFP Package Option 2: iCE40

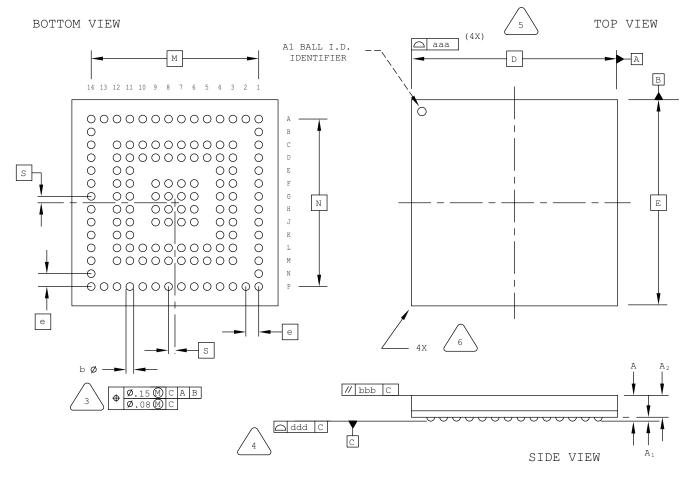
Dimensions in Millimeters





132-Ball csBGA Package Option 2: iCE40

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



4

5

6

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

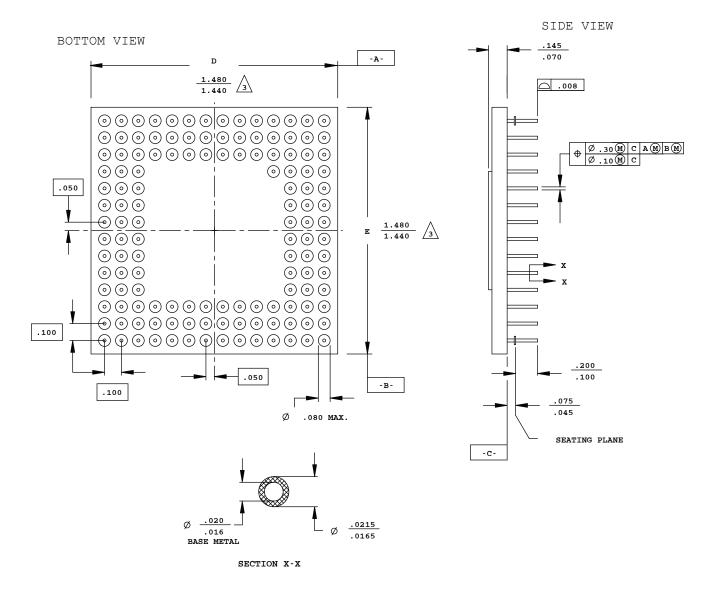
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	-	-
A2	-	_	0.85
D/E	8	.00 BSC	
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa			0.10
bbb	_	_	0.10
ddd	_	_	0.08



133-Pin CPGA Package

Dimensions in Inches



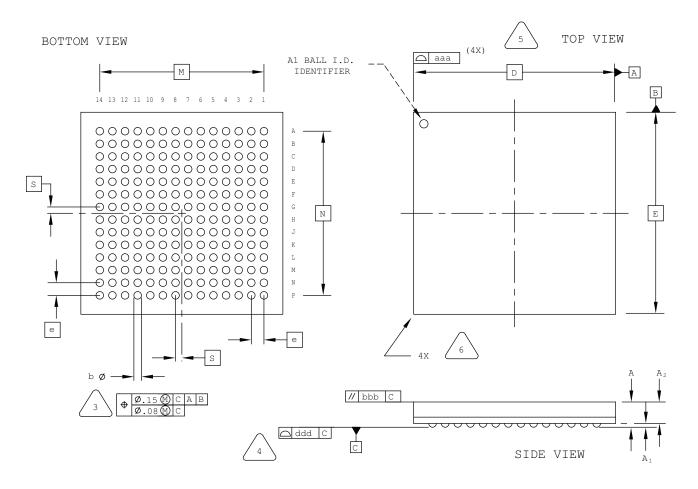
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .006 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .003 INCHES MAXIMUM PER SIDE.



196-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



4

5

6

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

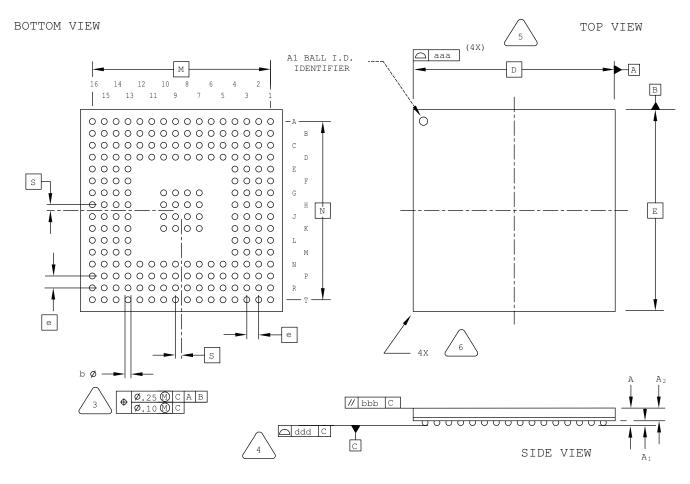
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	-	-
A2	_	_	0.85
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	_	_	0.10
bbb	-	-	0.10
ddd	-	-	0.08



208-Ball ftBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



4

5

6

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

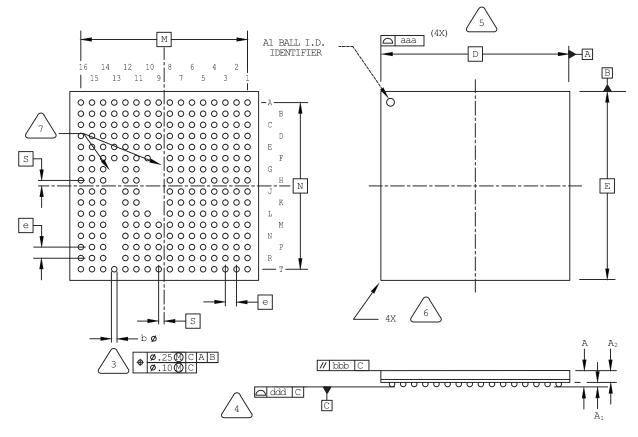
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

SYMBOL	MIN.	NOM.	MAX.
A	1.25	1.40	1.55
A1	0.30	-	-
A2	-	-	1.25
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
е	1.0 BSC		
aaa	_	_	0.20
bbb	-	-	0.25
ddd	_	_	0.12



237-Ball ftBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- $\sqrt{3}$

4

5

6

7

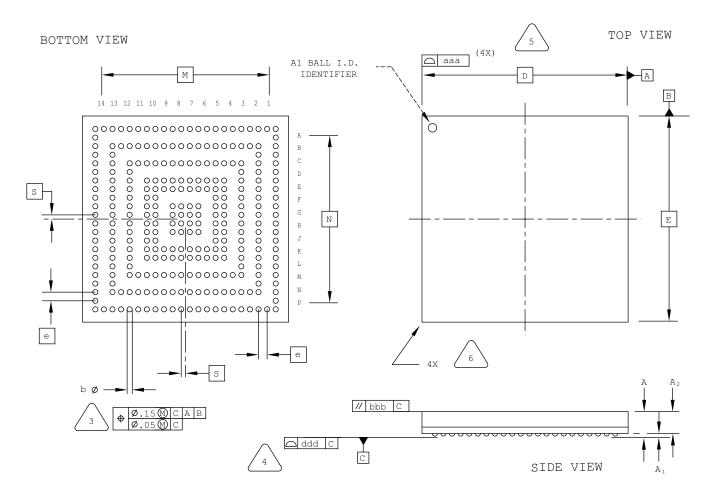
- DIMENSION "D" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- DEPOPULATED 13G TO 13R, 10G TO 10K, AND 9F TO 9L.

SYMBOL	MIN.	NOM.	MAX.
A	1.40	1.55	1.70
A1	0.30	-	-
A2	_	_	1.24
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
e	1.0 BSC		
aaa	-	-	0.20
bbb	_	-	0.25
ddd	_	_	0.15



284-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES 1. PER ANSI Y14.5M. 2. ALL DIMENSIONS ARE IN MILLIMETERS. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER 3 PARALLEL TO PRIMARY DATUM C PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL 4 CROWNS OF THE SOLDER BALLS. BILATERAL TOLERANCE ZONE IS APPLIED 5 TO EACH SIDE OF THE PACKAGE BODY.

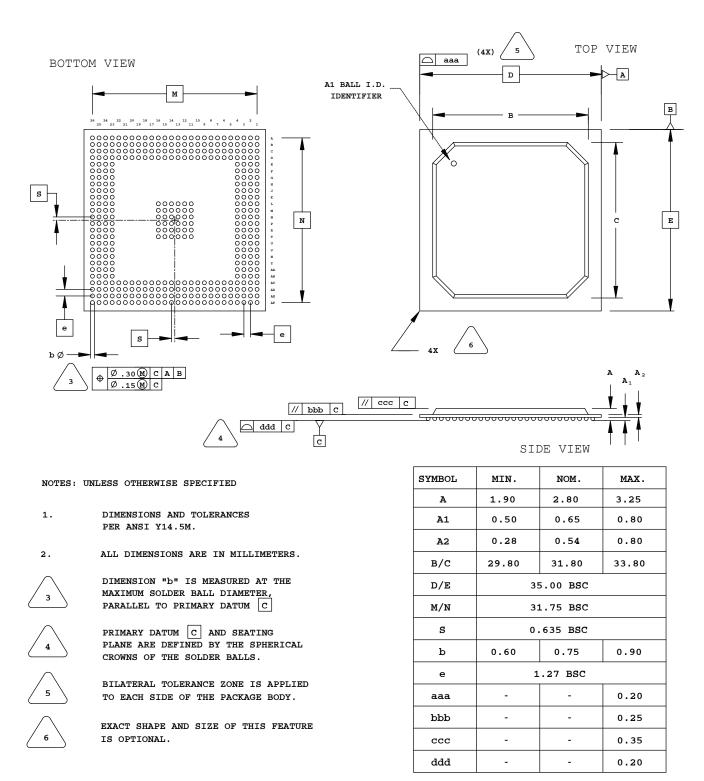
6

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	-	_
A2	_	_	0.85
D/E	12.00 BSC		
M/N	10.50 BSC		
S	0.25 BSC		
b	0.25	0.31	0.37
е	0.50 BSC		
aaa	_	_	0.10
bbb	_	_	0.10
ddd	_	_	0.08



388-Ball BGA Package

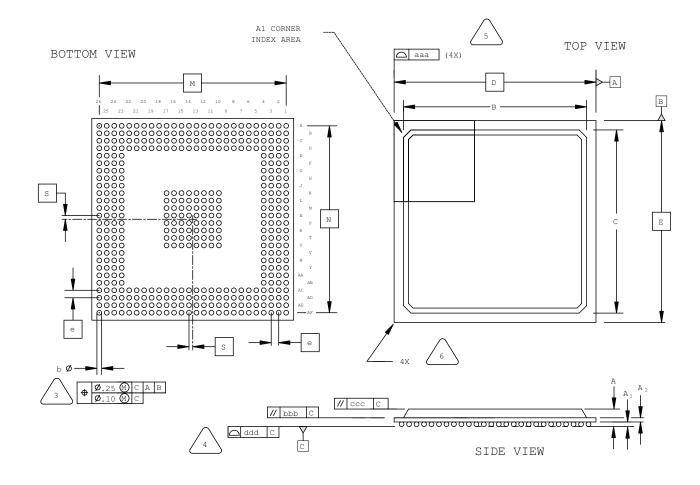
Dimensions in Millimeters





416-Ball fpBGA Package

Dimensions in Millimeters



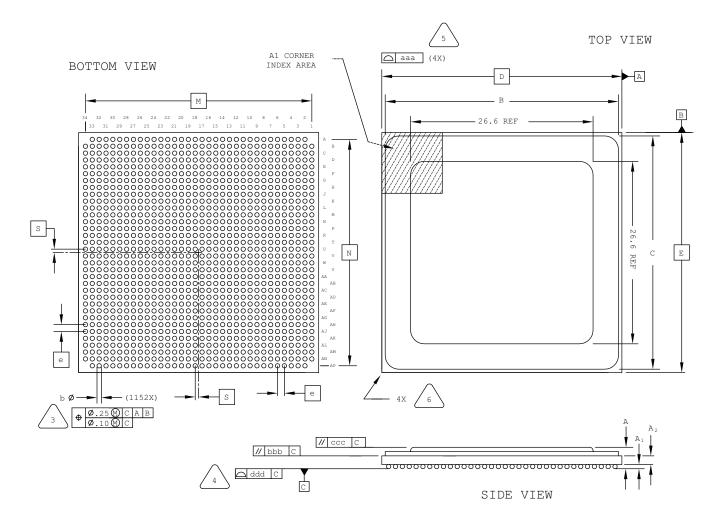
NOTES:	UNLESS OTHERWISE SPECIFIED
1.	DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2.	ALL DIMENSIONS ARE IN MILLIMETERS.
3	DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4	PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5	BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6	EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	23.80	24.80	25.80
D/E	27.00 BSC		
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20



1152-Ball Organic fcBGA Package Option 1: LatticeSC/SCM40

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

6

1.	DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2.	ALL DIMENSIONS ARE IN MILLIMETERS.

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

SYMBOL	MIN.	NOM.	MAX.	
A	2.55	2.90	3.25	
A1	0.35	0.50	0.65	
A2	1	1.20 REF		
B/C	34.25	34.50	34.75	
D/E	35.00 BSC			
M/N	33.00 BSC			
S	0.50 BSC			
b	0.50	0.60	0.70	
е	1.00 BSC			
aaa	-	-	0.20	
bbb	-	-	0.25	
ccc	-	-	0.35	
ddd	-	-	0.20	